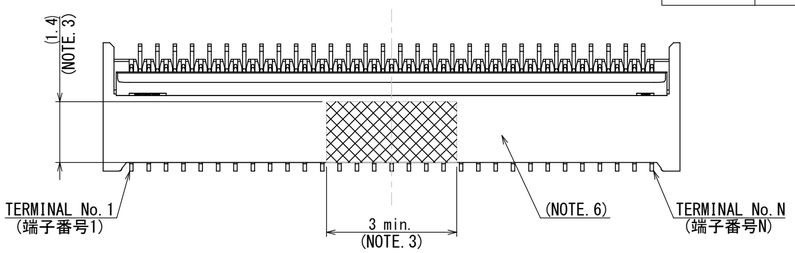
図面番号(DRAWING NO.) SJ113749

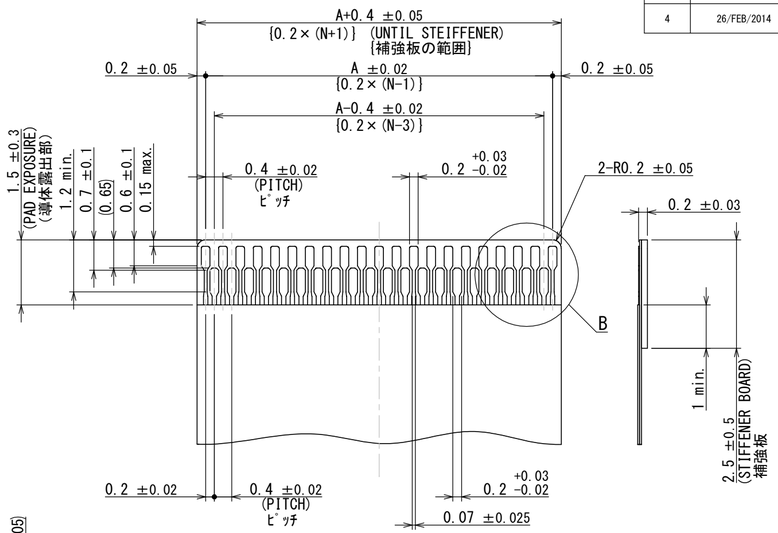
版数 VER.	年月日 DATE	CN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	20/JUN/2013	006616	ADDED ITEM. ADDED FIGURE OF APPLICABLE FPC. (REDACTION MARK:3) 4		K.ASHIBU	H.YOKOO	M.KIKUCHI
3	27/AUG/2013	007323	CHANGED FIGURE OF APPLICABLE FPC. (REDACTION MARK:2) 4		K.ASHIBU	H.YOKOO	M.KIKUCHI
4	26/FEB/2014	008611	ADDED ITEM. ADDED FIGURE OF APPLICABLE FPC. ETC. (REDACTION MARK:4)		K.ASHIBU	H.YOKOO	M.KIKUCHI

WISDOM承認 2014/02/28

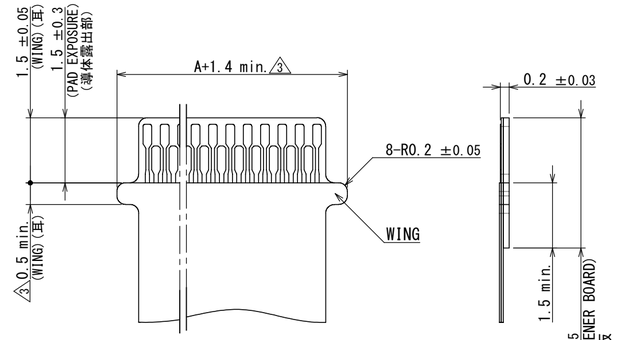
TABLE 2. DIMENSIONS 2 4

PIN COUNT	A	B
23	4.4	5.7
41	8.0	9.3
45	8.8	10.1
51	10.0	11.3
61	12.0	13.3



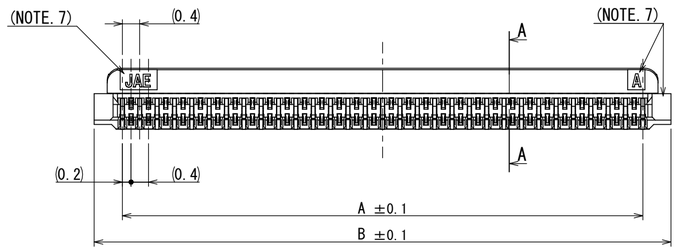


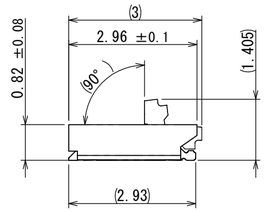
(IN THE CACE OF WITHOUT WINGS)
(耳無しの場合) 2

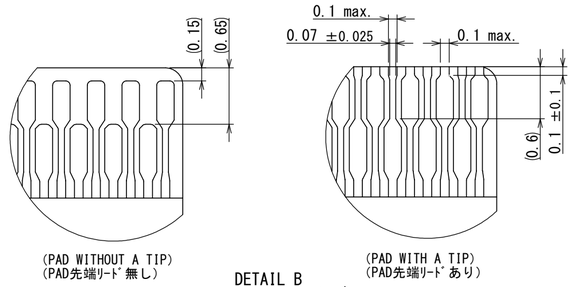


(IN THE CACE OF WITH WINGS)
(耳有りの場合) 2

APPLICABLE F.P.C. DIMENSION(REF.)
適合FPC寸法(参考)



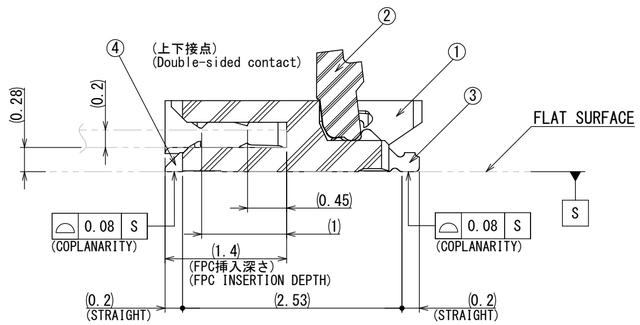




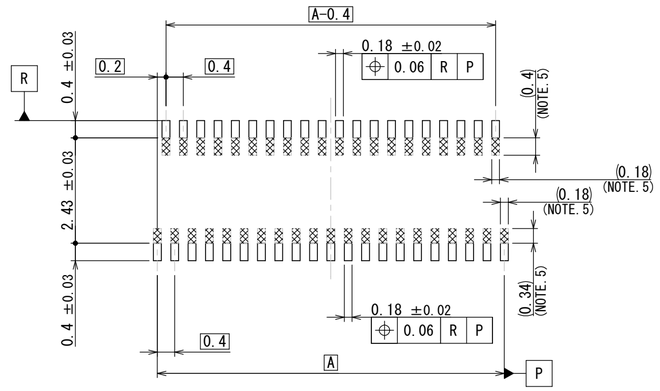
(PAD WITHOUT A TIP)
(PAD先端ﾘｰﾄﾞ無し)

(PAD WITH A TIP)
(PAD先端ﾘｰﾄﾞあり)

DETAIL B
SCALE (20 : 1) 4



SECT A-A
SCALE (20 : 1)



FPC INSERTION SIDE
(FPC挿入側)

APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

NOTE
1. REFER TO TABLE1 FOR RECOMMENDED FPC COMPOSITION.
2. A NICKEL BARRIER EXISTS BETWEEN CONTACT POINT ADN TAIL.
3. THE DIMENTIONS OF VACCUMING COVER AREA.
4. RECOMMENDED F.P.C. PUNCHER DIRECTION ARE FROM CONDUCTOR SIDE TO STIFFNER FILME SIDE.
5. IN THIS RANGE, WIRING OF A PATTERN IS FORBIDDEN EXCEPT FOR THE PATTERN ELECTRICALLY CONNECTED WITH PAD WHICH EACH RANGE TOUCHES.
6. LOT NUMBER IS MARKED ON THE TOP PORTION OF THE CONNECTOR.
7. THE FOLLOWING ITEMS ARE OPTIONAL: THE DIRECTION AND FORM OF THE COMPANY TRADE MARK, CONFIGURATION AND FORM OF TOOLING ID MARK, AND THE NUMBER AND CONFIGURATION OF SINK-PREVENTING HOLE.
8. THIS PRODUCT IS HALOGEN-FREE

注記
1. 推奨FPC構成はTABLE1参照のこと。
2. ｺﾝﾀｸﾄ接点とSMT部の間にはﾆｯｹﾙﾊﾞﾘｱが有ります。
3. 吸着ｴﾘｱを示す。
4. FPCの金型抜き方向は、導体側から補強板側を推奨します。
5. この範囲では、それぞれの範囲が接するﾊﾟｯﾄﾞと電気的に接続されるﾊﾟﾀｰﾝを除いて、ﾊﾟﾀｰﾝの配線は禁止となります。
6. ﾛｯﾄ番号がｺﾈｸﾀ上面に表記されます。
7. 社標表示部の形状･社標の向き、金型ﾏｰｸ表示部の形状･配置、ひけ防止孔の形状･個数は任意である。
8. 本製品はﾊﾛｹﾞﾝﾌﾘｰ品です。

TABLE 1. RECOMMENDED F.P.C. COMPOSITION

COMPOSITION 層名		RECOMMENDED 推奨
GOLD PLATING 金めっき	ELECTROLYSIS PLATING 電解めっき	0.1μm MIN.
COPPER 銅箔	ROLLED MATERIAL 圧延銅	18μm MAX.
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	—
BASE FILM ﾍﾞｰｽﾌｨﾙﾑ	POLYIMIDE ﾎﾟﾘｲﾐﾄﾞ	25μm
ADHESIVE 接着剤	THERMOSETTING ADHESIVE 熱硬化性	30μm MAX.
REINFORCE PLATE 補強板	POLYIMIDE ﾎﾟﾘｲﾐﾄﾞ	—

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	図番 DWG NO.
4	CONTACT2 ｺﾝﾀｸﾄ2	(N+1)/2	PHOSPHER BRONZE りん青銅	PARTIAL GOLD OVER NICKEL(Au0.1μm MIN.) ﾆｯｹﾙ上部分金(金0.1μm 以上)	
3	CONTACT1 ｺﾝﾀｸﾄ1	(N-1)/2	PHOSPHER BRONZE りん青銅	PARTIAL GOLD OVER NICKEL(Au0.1μm MIN.) ﾆｯｹﾙ上部分金(金0.1μm 以上)	
2	ACTUATOR ｱｸﾁｭｴｰﾀ	1	HEAT RESISTING PLASTICS 耐熱ﾌﾟﾗｽﾁｯｸ		COLOR : NATURAL 色相 : 自然
1	BASE INSULATOR ﾍﾞｰｽｲﾝｼｭﾚｰﾀ	1	HEAT RESISTING PLASTICS 耐熱ﾌﾟﾗｽﾁｯｸ		COLOR : BLACK 色相 : 黒

仕様書(SPECIFICATION) JACS-10807-* JAHL-10807	第1版(ORIGINAL DATE) 09/MAY/2013	尺度(SCALE) 10:1	シリーズ(SERIES) FR02
一般公差(GENERAL TOLERANCE) 寸法(DIMENSION) ±0.8 / ×.× ±0.4 / ×.×× ±0.1 / ×.××× ± 角度(ANGLES) ×° ± / ×°×' ± 単位(UNIT) : mm	製図 DR.	名称(TITLE) FR02C0**JA1 (**:Pin count)	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
	担当 CHK. K.ASHIBU		
	査閲 APPD. H.YOKOO		
	承認 APPD. M.KIKUCHI	質量(MASS)	図面番号(DRAWING NO.) SJ113749
			SIZE A2 / 版数(VER.) 4

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